

## Introduction

The microcontrollers of the STM8AF Series, featuring different memory densities, packages and peripherals, are designed for automotive applications.

This document describes how to use them in the context of a safety-related system (STM8A-SafeASIL functional safety package), specifying the user's responsibilities for installation and operation, in order to reach the targeted safety integrity level.

This manual applies to the following STM8AF products:

- the STM8AF62 line, which is the mainstay of the automotive STM8A 8-bit MCU:
  - low density devices with 8 Kbytes of Flash memory: STM8AF6223/26
  - medium density devices with 16 to 32 Kbytes of Flash memory: STM8AF624x, STM8AF6266/68, STM8AF612x/4x and STM8AF6166/68
  - high density devices with 32 to 128 Kbytes of Flash memory: STM8AF6269/8x/Ax and STM8AF6178/99/9A
- the STM8AF52 line: STM8AF automotive MCUs with CAN:
  - high density devices with 32 to 128 Kbytes of Flash memory: STM8AF52xx and STM8AF51xx

System designers can avoid going into the details of the ISO26262 functional safety standard application to the STM8AF microcontrollers by following the indications reported in this manual.

This manual is written in compliance with ISO 26262. It also indicates how to use the STM8AF MCUs in the context of other functional safety standards such as IEC 61508.

The safety analysis summarized in this manual takes into account the variation in terms of memory size, number of internal peripherals and the different packages available among the different part numbers of STM8AF microcontrollers.

This manual has to be read along with the technical documentation on related part numbers available on [www.st.com/stm8](http://www.st.com/stm8).

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# 1 About this document

## 1.1 Purpose and scope

This document is addressed at system designers willing to evaluate the safety of their solution. It describes how to use STM8AF microcontrollers in the context of a safety-related system, specifying the user's responsibilities for installation and operation, to reach the desired safety integrity level.

## 1.2 Terms and abbreviations

**Table 1. Terms and abbreviations**

Acronym	Definition
AoU	Assumptions to Use
ASIL	Automotive Safety Integrity Level
CCF	Common Cause Failure
COTS	Commercial Off-the-Shelf
CPU	Central Processing Unit
CRC	Cyclic Redundancy Check
DC	Diagnostic Coverage
DTI	Diagnostic Test Interval
FIT	Failure In Time
FTTI	Fault Tolerant Time Interval
FMEA	Failure Mode Effect Analysis
FMEDA	Failure Mode Effect Diagnostic Analysis
HFT	Hardware Fault Tolerance
HW	Hardware
INTC	Interrupt Controller
LFM	Latent Fault Metric
MCU	Microcontroller Unit
MPF	Multiple Point Failures
MPFDI	Multiple Point Fault Detection Interval
NVIC	Nested vector interrupt controller
PMHF	Probabilistic Metric for random Hardware Failures
QM	Quality Management
SFF	Safe Failure Fraction
SIL	Safety Integrity level
SEooC	Safety Element Out of Context
SPF	Single Point Fault
SPFM	Single Point Fault Metric
SW	Software

## 1.3 Reference normative

This document is written in compliance with the ISO 26262 international standard for functional safety of electrical and/or electronic (E/E) systems within road vehicles.

The versions used as reference are:

- ISO/IS 26262-1 – 9:2011(E)
- ISO/IS 26262-10:2012(E)

This safety manual follows the list of recommended contents in Annex A, clause A.3.10 of ISO 26262-10.

The other functional safety standard considered in this manual is the following:

- IEC 61508:1-7 © IEC:2010.

## 1.4 Annexes

- [1] UM2138 FMEDA analysis for STM8AF Series MCUs
- [2] UM2139 FMEDA handling for STM8AF Series MCUs

UM2138 is a collection of FMEDA snapshots. It is a static document reporting the safety metrics computed for different detail levels (at microcontroller level and for microcontroller basic functions) for a given combination of safety mechanisms, a given set of assumptions and for a given part number. If a FMEDA computation sheet is needed, contact your local STMicroelectronics sales representative to receive information on expected delivery dates for specific MCU target part numbers.

UM2139 provides clarifications, guidelines and examples on how to handle the FMEDA results for STM8AF MCUs.

## 2 STM8AF device development process

The development process of a microelectronic device that is used in safety critical application takes into account the adequate management to reduce the probability of systematic faults introduced during the design phase.

ISO 26262-10 Annex A (“A.3.7: *Example of techniques or measures to detect or avoid systematic failures during design of a microcontroller*”) act as a guidance in tailoring the microcontroller standard design and manufacturer process to the compliance of ISO 26262 requirements. The checklist reported in the named Annex A (*Table A.8*) helps to collect all related evidences of a given real process.

### 2.1 STMicroelectronics standard development process

STMicroelectronics (ST) serves four industry domains:

- Standard products.
- Automotive products: ST automotive products are AEC-Q100 compliant. They are subject to specific stress testing and processing instructions in order to achieve the required quality levels and product stability.
- Automotive safety: a subset of the automotive domain. ST uses as a reference the ISO 26262 Road vehicles Functional safety standard. ST supports customer inquiries regarding product failure rates and FMEDA to support hardware system compliance to established safety goals. ST provides products that are safe in their intended use, working in cooperation with customers to understand the mission profile, adopt common methods and define countermeasures for residual risks.
- Medical products: ST complies with applicable regulations for medical products and applies due diligence in the development and validation of these products.

STMicroelectronics product development process, compliant with the ISO/TS 16949 standard, is a set of interrelated activities dedicated to transform customer specification and market or industry domain requirements into a semiconductor device and all its associated elements (package, module, sub-system, application, hardware, software and documentation), qualified respecting ST internal procedures and able to be manufactured using ST internal or subcontracted technologies.



## 3 STM8AF safety architecture

This section describes the safety architecture to implement when using STM8AF microcontrollers for automotive applications.

### 3.1 Introduction

The STM8AF microcontroller described in this document is a Safety Element out of Context (SEooC), that is, a safety element that can be used in different safety applications.

The aim of this section is to define the context of the analysis in terms of assumptions with respect to reference safety requirements as also assumptions with respect to the design external to that SEooC.

As a consequence of the SEooC approach, the goal is not to provide an exhaustive hazard and risk analysis of the system around the microcontroller, but rather to list the system-related information (such as the application-related assumptions for dangerousness factors, frequency of failures and diagnostic coverage already guaranteed by the application) that have been considered during the following steps of the analysis.

#### 3.1.1 Definition of the SEooC

The automotive industry develops generic elements for different applications and for different customers. These generic elements can be developed concurrently and by different companies in different tiers of the supply chain, as a distributed development. Assumptions are made both on the requirements (including safety requirements) on the element at higher levels of design and also on the design external to the element.

In a safety context, these elements can be developed as a “Safety Element out of Context” (SEooC), as described in ISO 26262-10, Clause 9.

According to ISO 26262, a “safety element out of context (SEooC)” is a safety-related element that is not developed for a specific item, i.e. in the context of a particular vehicle. A SEooC can be a system, an array of systems, a subsystem, a software component or a hardware component.

This document considers the STM8AF as a SEooC to whom it is required to have an ASIL capability, up to and including ASILB, i.e. it can be used in ASILA and ASILB environments.

### 3.2 STM8AF as a SEooC

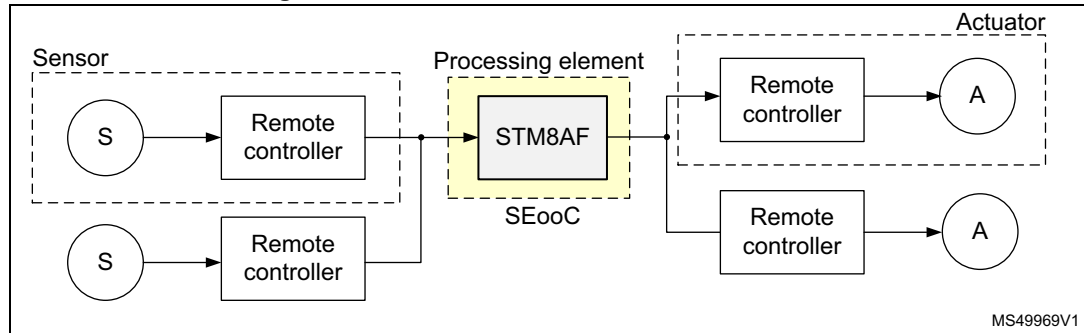
The STM8AF is a general purpose RISC microcontroller, suitable for embedded applications and, in particular, for safety related applications.

For a detailed description of the STM8AF functionality refer to the microcontroller technical reference manuals, available on [www.st.com](http://www.st.com).

In this document, the SEooC is identified as the STM8AF microcontroller (MCU), referenced as a functional block inserted in a system defined by [Figure 1](#). The MCU acts as the processing unit of the system, i.e. acquiring field data from sensors, processing them according to the implemented algorithm, and taking decisions that bring to specific

commands to external actuators. The MCU is connected directly or indirectly to sensors and actuators through communication busses.

**Figure 1. Definition of the STM8AF as a SEooC**

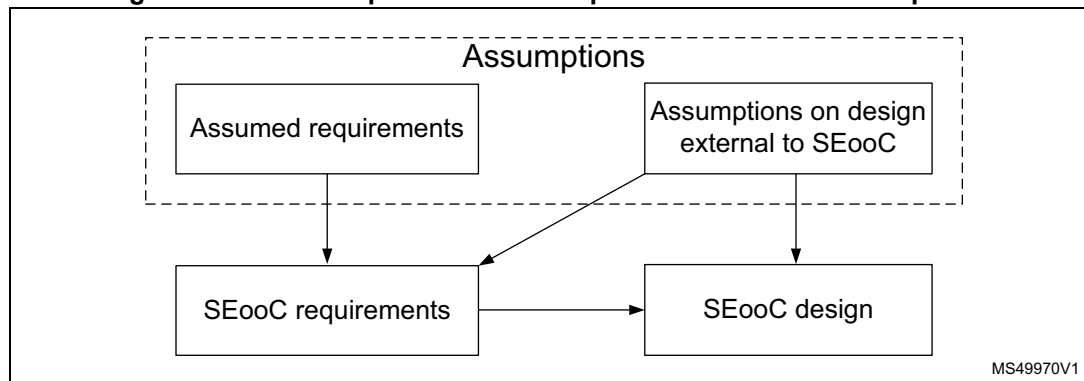


Other components, like the external HW components needed to guarantee either the functionality of the STM8AF (external memory, clock quartz) or its safety (e.g. the external watchdog, voltage supervisors) can be connected to the SEooC.

### 3.3 Assumed safety requirements

A SEooC is developed, according to ISO 2626-10 clause 9, on the basis of assumptions for its intended functionality, use and context, including external interfaces (Figure 2).

**Figure 2. Relationship between assumptions and SEooC development**



The validity of the aforementioned assumptions is checked, in the context of the actual item, after the integration of the SEooC.

In this document it is assumed that the concept specification, the hazard and risk analysis, the overall safety requirement specification and the consequent allocation have determined the assumed safety requirements reported in Table 2.

Table 2. List of STM8AF assumed requirements

ID	Assumed requirement
AR01	The SEooC is defined as the STM8AF playing the role of processing unit, as in <a href="#">Figure 1</a> .
AR02	Failures in STM8AF HW part leading to wrong execution of the application program and/or wrong data computations shall be mitigated to fulfil the ASILB capability, i.e. <ul style="list-style-type: none"> <li>– single-point fault metric at the HW part level at least 90%</li> <li>– latent point fault metric at the HW part level at least 60%</li> </ul>
AR03	The STM8AF is assumed to be integrated in a product with a lifetime up to 10 years
AR04	In accordance with ISO 26262-5, 6.4.8 – Note 1, it is assumed that the MPFDI (Multiple-Point Fault Detection Interval) is equal to or lower than to the item's "power-up to power-down" cycle (i.e. 1 hour).
AR05	Safety Integrity Level required for the STM8AF is ASILB
AR06	It is assumed a FTTI budget allocated to the STM8AF of 250 msec <sup>(1)</sup>
AR07	It is assumed that the STM8AF implements a safe state defined as one in which either: <ul style="list-style-type: none"> <li>– the application software running on the MCU is informed of the presence of a fault and a reaction is possible<sup>(2)</sup>, or</li> <li>– if the application software cannot be informed, the MCU reset is executed<sup>(3)</sup>.</li> </ul>
AR08	On the STM8AF SEooC will not be executed together ASIL, QM and/or not- safety related software <sup>(4)</sup>

1. FTTI value is used for reference only. The end user shall verify that the FTTI value of the final application is compatible with the requirements in terms of execution of periodical software-based test (refer to [Section 3.6](#)).
2. The end user shall take into account that hardware random failures affecting the STM8AF can compromise the MCU capability of operating properly (for example failure modes affecting the program counter prevent the correct execution of software).
3. According to ISO 26262-1, the safe state is the operating mode of an item without unreasonable level of risk. The ultimate definition of the safe state depends on the end user application
4. The possibility for the SEooC to execute either ASIL, QM and non-safety-related functions together has been excluded because not supported by dedicated hardware.

### 3.3.1 The target safety metrics (ASIL, SPFM, LFM and PMHF)

According to [AR05](#), the target for the safety functions is ASILB; therefore every consideration about absolute and relative safety metrics will take ASILB targets, as reported in [Table 3](#).

Table 3. Target safety metric values at the item level

Safety metric defined	Target value (system level)	Target value (SEooC level)	Metric type
Single-point fault metric (SPFM)	≥ 90%	≥ 90%	Relative
Latent-fault metric (LFM)	≥ 60%	≥ 60%	Relative
Probabilistic metric for random hardware failures (PMHF)	100 FIT	10 FIT	Absolute

Even if safety metrics are defined at item (i.e. at car) level for ISO 26262, the functional safety standard explicitly foresees the computation of those metrics at a lower level.

In this document any claim and computation in terms of safety metrics will be done on the activity safety scope represented by the SEooC block diagram reported in [Table 1](#).

The budget of the PMHF given to the SEooC must be (if possible) lower than 10% of the overall PMHF budget of the safety goal, and therefore (for ASILB) the budget for the STM8AF is  $10\% * 100 \text{ FIT} = 10 \text{ FIT}$ .

### 3.3.2 The assumed target time intervals (FTTI and MPFDI)

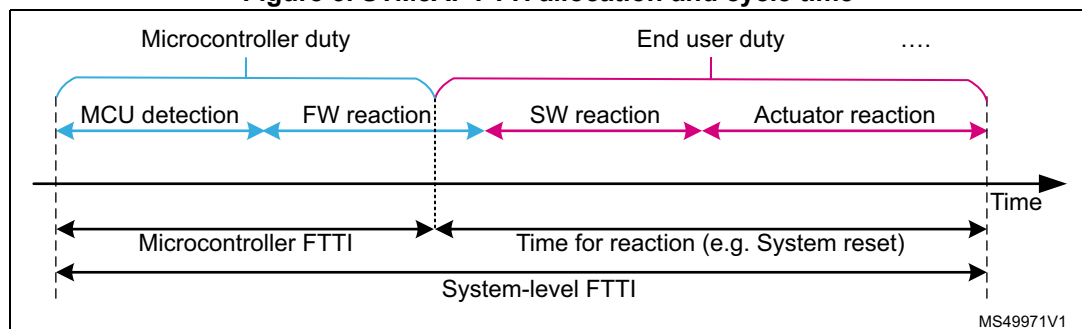
As illustrated in *ISO 26262-1:2001 - Figure 4 - Fault reaction time and fault tolerant time interval*, a system must be able to detect faults and move to safe state before a fault can become a system level hazard.

In ISO 26262-1, the Fault Tolerant Time Interval (FTTI) is defined as the time span in which a fault (or faults), can be present in a system before a hazardous event occurs.

Moreover, according to ISO 26262-1:2011, the Multiple-Point Fault Detection Interval (MPFDI) is the time span to detect multiple-point fault before it can contribute to a multiple-point failure.

From a system point of view, the STM8AF MCU is a safety-related element, to which a portion of the FTTI system budget is associated. As shown in [Figure 3](#), the portion of FTTI assigned to a SEooC (in this case the STM8AF) strongly depends on the application.

**Figure 3. STM8AF FTTI allocation and cycle time**



In this document, according to ISO 26262-10, 9.2.3.3 d) it is assumed that any implemented safety mechanisms related to the STM8AF will complete its functions in less than the assigned FTTI budget time reported in [AR06](#).

This value must be considered as a reference, and can be changed by the MCU/system integrator according to its own needs.

It is worth noting that according to ISO 26262-5, 7.4.3.3 a single point fault shall be detected within the FTTI budget allocated to the component.

In this document, in accordance with ISO 26262-5:2011, 6.4.8 – Note 1, it is assumed that the MPFDI is equal to or lower than the item's “power-up to power-down” cycle (i.e. one driving cycle), [AR04](#).

### 3.4 Electrical specifications and environment limits

The user must not exceed the electrical specification and the environmental limits defined in the list below, as reported in STM8AF datasheets, to guarantee its own safety integrity:

- absolute maximum rating
- operating conditions.

Due to the large number of STM8AF products, the related user manuals/datasheets are not listed in this document; the user is responsible to carefully check the above reported limits in the technical documentation on the related part number available on [www.st.com](http://www.st.com).

### 3.5 Systematic safety integrity

Due to known device limitations for STM8AF automotive MCUs, the user must follow the errata sheets available on [www.st.com](http://www.st.com) to avoid the introduction of systematic failures.

### 3.6 Safety mechanisms/measures

This section lists all the safety mechanisms/measures (hardware, software and application level) considered in the safety analysis of the microcontrollers of the STM8AF Series.

According to ISO 26262-1, “...a safety mechanism is a technical solution implemented by Electrical/Electronic (E/E) functions or elements, or by other technologies, to detect faults or control failures in order to achieve or maintain a safe state”.

It is expected that users are familiar with the STM8AF architecture, and that this document is used in conjunction with the related device datasheet, user manual and reference information. Therefore, in order to avoid any mistake and reduce the amount of information to be shown, no functional details are included in this document.

Note that the part numbers of the STM8AF series represent different combinations of peripherals (for instance, some of them are not equipped with CAN peripheral). To reduce the number of documents and avoid information-less repetitions, the current safety manual addresses the overall possible peripherals available in the targeted part numbers. Users have to select which peripherals are really available on their devices, and discard the meaningless recommendations accordingly.

The implementation guidelines reported in the following section are for reference only. Read the following definitions:

- **end user:** the final user of STM8AF, in charge of integrating the MCU in a real application (for example an electronic control board)
- **application software:** the actual software running on the STM8AF, used to implement the safety function.

#### 3.6.1 STM8AF core

##### Periodical core self-test software - CPU\_SM\_0

Permanent faults affecting the CPU are addressed through a dedicated software test executing a sequence of instructions and data transfers.

The software test is built around well-known techniques already addressed by ISO 26262-5, D.2.3.1 (“Self-test by software: limited number of patterns (one channel)”). The

processing unit (CPU) is tested for functional correctness by applying at least one pattern per instruction. The testing of the same class of instruction with multiple not-trivial patterns in order to involve each operand's input and output bits, at least once equal to "0" and once equal to "1", is highly recommended. The accumulation by means of not-trivial computation (e.g. XOR) of the single instruction test result on the basis of the concept of signature is highly recommended. The safety analysis of the CPU hardware has shown that a stress-test for the pipeline structure is highly recommended.

The overall test software suite is assumed to be periodically executed with a time period compatible with the ISO 26262 requirements for the relationship between FTTI and the diagnostic test interval (DTI).

### **Control flow monitoring in application software - CPU\_SM\_1**

A significant part of the failure distribution of STM8AFcore for permanent faults is related to failure modes directly related to program counter loss of control or hang-up. Due to their intrinsic nature, such failure modes are not addressed by a standard software test method based on the execution of sequences of instruction/data access and consequent checks. Therefore it is necessary to implement a run-time control of the application software flow, in order to monitor and detect deviation from the expected behavior. Linking this mechanism to watchdog firing assures that severe loss of control (or, in the worst case, a program counter hang-up) will be detected within DTI.

This diagnostic measure also contributes to the transient fault detection affecting the program counter and branch execution subpart in STM8AFcore.

The guidelines for the implementation of the method are the following:

- The different internal states of the application software is well documented and described (the use of a dynamic state transition graph is encouraged).
- The monitoring of the correctness of each transition between different states of the application software is implemented.
- The transition through all expected states during the normal application software program loop is checked.
- The function in charge of triggering the system watchdog is implemented in order to constrain the triggering (preventing the watchdog reset) also to the correct execution of the above-described method for program flow monitoring.

The use of the window feature of the independent watchdog (IWDG) (or an external one) helps to implement a more robust control flow mechanism fed by a different clock source. In any case the safety metrics do not depend on the watchdog in use (the adoption of independent or external watchdog contributes to the mitigation of dependent failures, see [Section 4.2.2: Clock](#)).

### **Double computation in application software - CPU\_SM\_2**

A timing redundancy for safety-related computation is considered to detect transient faults affecting the STM8AFsubparts devoted to mathematical computations and data access.

The guidelines for the implementation of the method are the following:

- The requirement needs to be applied only to safety-relevant computation, that is those that can interfere with the system safety functions. Such computation needs to be therefore carefully identified in the original application software source code.
- Both mathematical operation and comparison are intended as computation.
- The redundant computation for comparison could be implemented according to the following template:
  - Original code:
 

```
If (VarA > VarB) then { ( execute function) }
```
  - Modified code:
 

```
copyVarA:=VarA; copyVarB:=VarB;
If (VarA > VarB) then {
If (copyVarA <= copyVarB) then { (signal_error);
break } ( execute function)
}
```
- The redundant computation is implemented by using copies of the original data for second computation, and by using an equivalent formula if possible.
- End users are responsible to carefully avoid that the optimization features of the used compiler removes the timing redundancy introduced according to this current condition of use.

### Stack hardening for application software - CPU\_SM\_3

The stack hardening method is required to address faults affecting the CPU register bank. This method is based on source code modification, introducing information redundancy in register-passed information to the called functions.

The guidelines for the implementation of the method are the following:

- Pass also the redundant copy of the passed parameters values (possibly inverted) and execute a coherence check in the function.
- Pass also the redundant copy of the passed pointers and execute a coherence check in the function.

For the parameters that are not protected by redundancy, it is recommended to implement defensive programming techniques (plausibility check of passed values). For example enumerated fields are to be checked for consistency.

### Independent watchdog - CPU\_SM\_4

Using an external watchdog for the control flow monitoring method ([CPU\\_SM\\_1](#)) contributes to further reduce potential common cause failures, because the external watchdog will be clocked and supplied independently from the STM8AF.

## 3.6.2 Program Flash memory

### Periodical software test for Flash memory - FLASH\_SM\_0

Permanent faults affecting the system Flash memory (memory cells and address decoder) are addressed through a dedicated software test that checks the memory cell contents versus the expected value, using signature-based techniques. The use of CRC-based encryption for signature is encouraged.

Without information about the frequency of usage of different occupied Flash memory sections, in principle, all the area used by the Flash memory is assumed to be tested with a time period compatible with the ISO 26262 requirements for the relationship between FTTI and the diagnostic test interval (DTI).

### **Control flow monitoring in application software - FLASH\_SM\_1**

Permanent and transient faults affecting the system Flash memory (that is the memory cells and address decoder) can interfere with the access operation by the CPU, leading to wrong data or instruction fetches. Such wrong data and operation, if able to heavily interfere with the expected flow of the application software, are detected by strong control flow mechanism linked to a system watchdog. For more detailed implementation guidelines for such technique refer to safety mechanism [CPU\\_SM\\_1](#).

*Note: The implementation of the CPU\_SM\_1 automatically involves the FLASH\_SM\_1 implementation.*

## **3.6.3 Data EEPROM**

### **Information redundancy - EEP\_SM\_0**

To address permanent faults affecting the internal EEPROM bank it is required to implement information redundancy techniques. Possible techniques are:

- use redundant copies of safety relevant data and perform coherence check before use
- organize data in arrays and compute and check checksum field before use.

Due to their nature, data stored in EEPROM are typically managed directly by the end user application software, therefore it is reasonable to rely on methods implemented in the final software solution.

### **Software read-back after write operation - EEP\_SM\_1**

To address missing writes on EEPROM cells, it is required that the application software executes a read-back of written data after an update of the EEPROM values. Missing writes will be handled as a hardware fault.

## **3.6.4 RAM**

### **Periodical software test for RAM - RAM\_SM\_0**

To address permanent faults affecting RAM data cells and address decoder it is required to execute a periodical software test on the system RAM. The selection of the algorithm ensures the target coverage for both the RAM cells and the address decoder. The end user provides also evidences of the effectiveness of the coverage of the selected method.

The overall test software suite is assumed to be periodically executed with a time period compatible with the ISO 26262 requirements for the relationship between FTTI and the diagnostic test interval (DTI).

### **Stack hardening for application software - RAM\_SM\_1**

The stack hardening method is used to enhance the application software robustness to RAM faults affecting the address decoder. The method is based on source code modification, introducing information redundancy in the stack-passed information to the



called functions. This method is relevant in case the combination between the final application software structure and the compiler settings requires a significant use of the stack for passing function parameters.

The guidelines for the implementation of the method are the following:

- Pass also the redundant copy of the passed parameters values (possibly inverted) and execute a coherence check in the function.
- Pass also the redundant copy of the passed pointers and execute a coherence check in the function.
- For parameters that are not protected by redundancy, implement defensive programming techniques such as the plausibility check of the passed values (for example to check the consistency of enumerated fields).

### **Information redundancy for safety-related variables in application software - RAM\_SM\_2**

To address transient faults affecting RAM controller and RAM cells, it is required to implement information redundancy of the safety-related system variables stored in the RAM.

The guidelines for the implementation of this method are the following:

- The system variables that are safety-related (in the sense that a wrong value read in the RAM affects the safety functions) are well-identified and documented.
- The arithmetic computation and/or decision based on such variables are/is executed twice and the two final results are compared.
- Non-numeric variables uses enumerated-type constant values for coding, avoiding trivial patterns (all-0x00 or all-0xFF); application software checks for consistence the value assumed by the variables, when used
- Numeric variables are grouped and protected by means of a checksum (for instance, computed by XOR), updated each variable overwriting and checked at least once per FTTI.

Note that the implementation of this safety method shows a partial overlap with an already planned method for STM8AFcore ([CPU\\_SM\\_1](#)); optimizations in implementing both methods are therefore possible (see the description of the [CPU\\_SM\\_1](#)).

## **3.6.5 Boot ROM**

### **Control flow monitoring in application software - ROM\_SM\_0**

The boot loader starts executing after reset. Permanent and transient faults affecting the boot ROM can leads to wrong execution of the application software at the end of the boot procedure. Such alteration is detected by a strong control flow mechanism linked to a system watchdog. For more detailed implementation guidelines of this technique refer to safety mechanism [CPU\\_SM\\_1](#).

*Note:* The implementation of the [CPU\\_SM\\_1](#) automatically involves the [ROM\\_SM\\_0](#) implementation.

### 3.6.6 Basic enhanced CAN (beCAN)

#### Periodical read-back of configuration registers - CAN\_SM\_0

This diagnostic measure that is typically referred to as “Read Back Periodic by Software of Configuration Registers” executes a periodical check of the configuration registers of beCAN peripheral respect to its expected value that is previously stored in the RAM and adequately updated after each configuration change. It mainly addresses the transient faults affecting the configuration registers, detecting bit flips. The register test is executed at least once per DTI in order to be able to claim the related diagnostic coverage.

#### Protocol error signals - CAN\_SM\_1

The CAN protocol error counters, which are entirely managed by the module at hardware level despite being conceived to detect network-related abnormal conditions, are able to contribute to the detection of the faults leading to error messages generation.

Handling such error signals at application level of is a common technique in embedded applications.

#### Information redundancy techniques on messages, including End to End safing - CAN\_SM\_2

The CAN communications are protected by addressing both the permanent and transient faults with the redundant information technique that includes the End to End Safing.

For the implementation of redundant information, it is possible to adopt a different approach:

- Multiple sending of the same message, with comparison of the received results.
- Addition by the sender of a checksum field to the message to be verified by the receiver.

In case the checksum field approach is adopted, the selection of the algorithm for checksum computation will ensure a similar protection against message corruption as the one ensured by a full redundancy.

For End to End Safing, additional measures are implemented:

- Additional field in payload allowing the unique identification of sender/receiver, and coherence check by receiver side.
- Timing monitoring of the message exchange (for example check the message arrival within the expected time window)
- Check of the message consistence using a message counter in the additional payload field and checking the right sequence of messages on the receiver side.

The use of a safe communication protocol such as PROFIsafe is recommended for the correct implementation of this safety mechanism.

### 3.6.7 LINUART

#### Periodical read-back of configuration registers - LINUART\_SM\_0

This diagnostic measure that is typically referred to as “Read Back Periodic by Software of Configuration Registers” executes a periodical check of the configuration registers of LINUART respect to their expected value (previously stored in RAM and adequately updated after each configuration change). It mainly addresses transient faults affecting the

configuration registers, detecting bit flips . The registers test is executed at least once per DTI.

#### **Protocol error signal - LINUART\_SM\_1**

The LIN protocol errors signals (if used) despite being conceived to detect physical layer related abnormal conditions, are able to contribute to the detection to faults leading to error messages generation. For instance, option parity bit in data byte frame, overrun error.

Handling such error signals at application level is a common technique in embedded applications.

#### **Information redundancy techniques on messages - LINUART\_SM\_2**

The redundant information technique is used to protect the LIN/UART communications by detecting both the permanent and transient faults. There are two different approaches to implement this technique:

- multiple sending of the same message, with comparison of the received results
- addition by the sender of a checksum field to the message to be verified by the receiver.

In case the checksum field approach is adopted, the selection of the algorithm for checksum computation will ensure a similar protection against message corruption as the one ensured by a full redundancy. Theoretical demonstrations on coverage capability are admitted, the use of CRC coding is anyway suggested.

The above-reported approaches are equivalent; an additional criterion for the selection of the approach is the availability of a quick hardware support on the MCU platform, and the evaluation of the computation capability of the external device exchanging data with STM8AF.

### **3.6.8 USART**

#### **Periodical read-back of configuration registers - UART\_SM\_0**

This diagnostic measure that is typically referred to as “Read Back Periodic by Software of Configuration Registers” executes a periodical check of the configuration registers of USART respect to their expected value (previously stored in RAM and adequately updated after each configuration change). It mainly addresses transient faults affecting the configuration registers, detecting bit flips. The registers test is executed at least once per DTI.

#### **Protocol error signals - UART\_SM\_1**

The UART protocol errors signals (if used) are conceived to detect physical layer related abnormal conditions, and are able to contribute to the detection of faults leading to error messages generation (such as option parity bit in data byte frame, overrun error). Handling such error signals at application level is a common technique in embedded applications.

### Information redundancy techniques on messages - UART\_SM\_2

The redundant information technique is used to protect the USART communications by detecting both the permanent and transient faults. There are two different approaches to implement this technique:

- multiple sending of the same message, with comparison of the received results
- addition by the sender of a checksum field to the message to be verified by the receiver.

In case the checksum field approach is adopted, the selection of the algorithm for checksum computation will ensure a similar protection against message corruption as the one ensured by a full redundancy. Theoretical demonstrations on coverage capability are admitted – the use of CRC coding is anyway suggested.

The above-reported approaches are equivalent; an additional criterion for the selection of the approach is the availability of a quick hardware support on the MCU platform, and the evaluation of the computation capability of the external device exchanging data with STM8AF.

## 3.6.9 I2C

### Periodical read-back of configuration registers - IIC\_SM\_0

This diagnostic measure that is typically referred to as “Read Back Periodic by Software of Configuration Registers” executes a periodical check of the configuration registers of I2C respect to their expected value (previously stored in RAM and adequately updated after each configuration change). It mainly addresses transient faults affecting the configuration registers, detecting bit flips. The registers test is executed at least once per DTI.

### Protocol error signals - IIC\_SM\_1

The I2C protocol errors signals, despite being conceived to detect physical layer related abnormal conditions, are able to contribute to the detection of faults leading to error messages generation such as for instance the ACK assertion phase, and related checks.

Handling such error signals at application level is a common technique in embedded applications.

### Information redundancy techniques on messages - IIC\_SM\_2

The redundant information technique is used to protect the I2C communications by detecting both the permanent and transient faults. There are two different approaches to implement this method:

- multiple sending of the same message, with comparison of the received results
- addition by the sender of a checksum field to the message to be verified by the receiver.

In case the checksum field approach is adopted, the selection of the algorithm for checksum computation will ensure a similar protection against message corruption as the one ensured by a full redundancy. Theoretical demonstrations on coverage capability are admitted – the use of CRC coding is anyway suggested (also looking for the availability of a quick hardware support on the MCU platform).

The above-reported approaches are equivalent; an additional criterion for the selection is the evaluation of the computation capability of the external device exchanging data with STM8AF.

### 3.6.10 SPI

#### Periodical read-back of configuration registers - SPI\_SM\_0

This diagnostic measure that is typically referred to as “Read Back Periodic by Software of Configuration Registers” executes a periodical check of the configuration registers of SPI respect to their expected values previously stored in RAM and adequately updated after each configuration change. It mainly addresses transient faults affecting the configuration registers, detecting bit flips. The registers test is executed at least once per DTI.

#### Protocol error signals - SPI\_SM\_1

The SPI protocol errors signals, despite being conceived to detect physical layer related abnormal conditions, are able to contribute to the detection to faults leading to error messages generation such as, for instance, FIFO overrun and Mode error flags.

Handling such error signals at application level is a common technique in embedded applications.

#### Information redundancy techniques on messages - SPI\_SM\_2

The redundant information technique is used to protect the SPI communications by detecting both the permanent and transient faults. There are two different approaches to implement this method:

- multiple sending of the same message, with comparison of the received results
- addition by the sender of a checksum field to the message to be verified by the receiver.

In case the checksum field approach is adopted, the selection of the algorithm for checksum computation will ensure a similar protection against message corruption as the one ensured by a full redundancy. Theoretical demonstrations on coverage capability are admitted, the use of the hardware CRC computation unit built into SPI module is highly suggested.

The above-reported approaches are equivalent; an additional criterion for the selection is the evaluation of the computation capability of the external device exchanging data with STM8AF.

### 3.6.11 Analog to digital converter (ADC)

#### Periodical read-back of configuration registers - ADC\_SM\_0

This diagnostic measure that is typically referred to as “Read Back Periodic by Software of Configuration Registers” executes a periodical check of the configuration registers of ADC respect to their expected values , previously stored in RAM and adequately updated after each configuration change. It mainly addresses transient faults affecting the configuration registers, detecting bit flips. The registers test is executed at least once per DTI.

### Multiple acquisitions by application software - ADC\_SM\_1

To address the transient faults that affect the ADC module, it is required to implement a timing information redundancy scheme that executes multiple acquisitions of the same signal. This recommendation will most probably be satisfied by the end user application software. The usage of multiple acquisitions followed by average operations is a common technique in industrial applications where it is needed to survive with spurious EMI disturbs on sensor lines.

### Range check by application software - ADC\_SM\_2

To address permanent faults affecting ADC module, and also to address failure modes affecting the analogue section, it is required that the application software executes a range/plausibility checks on the measures coming from ADC acquisitions. The guidelines for the implementation of the method are the following:

- The expected data range to be acquired is investigated and adequately documented. Note that in a well-designed application it is unlikely that during normal operation an input signal has a value very close to or over the upper and below the lower rail limit (saturation in signal acquisition).
- If the application software is aware of the state of the system, this information has to be used in the range check implementation. For example, if the ADC value is the measurement of a current through a power load, reading an abnormal value (for instance a current flowing in opposite direction versus the load supply) may indicate a fault in the acquisition module.
- As the ADC module is shared between different possible external sources, the combination of plausibility checks on the different signals acquired helps to cover the whole input range in a very efficient way.

*Note:* The implementation of this safety mechanism is strongly application-dependent.

### Periodical software test for ADC - ADC\_SM\_3

To address permanent faults affecting ADC module, and also to address failure modes affecting the analogue section, it is required to execute a periodical test on the ADC acquisition section. The method is implemented by acquiring either the internal reference voltage or, alternatively, a reference voltage coming from the external (board) and connected to an input pin, and comparing to the expected value. This test is executed periodically at least once per DTI.

## 3.6.12 Advanced control and general purpose timers (TIM 1 and TIM 2/3)

As the advanced control and general purpose timers are equipped with different channels, each independent from the others, and possibly programmed to realize different features, the safety mechanism is selected individually for each channel.

### Periodical read-back of configuration registers –TIM\_SM\_0

This diagnostic measure that is typically referred to as “Read Back Periodic by Software of Configuration Registers” executes a periodical check of the configuration registers of TIMER respect to their expected values, previously stored in RAM and adequately updated after each configuration change. It mainly addresses transient faults affecting the configuration registers, detecting bit flips. The registers test is executed at least once per DTI.

### Dual channel redundancy for counting timers –TIM\_SM\_1

This method provides a high level of coverage for both permanent and transient faults on the addressed timers. The method is conceived to protect the timers with counting features, for example the timers dedicated to maintain a system time base and/or to generate a timed interrupt for the execution of service routines (like for instance general timing counters update/increase).

The guidelines for the implementation of the method are the following:

- In case of timer used as a time base, use one of the timers as time-base source in the application software, and the other one just for check. In that case the coherence check for the dual channel redundancy will be done at application level.
- In case of interrupt generation usage, use the first timer as main interrupt source for the service routines, and use the second timer to activate a “checking routine” that cross-checks the coherence between the timers.

### Dual channel redundancy for input capture timers - TIM\_SM\_2

This method, based on dual channel redundancy scheme, provides a high level of coverage for both the permanent and transient faults on the addressed timers. It is conceived to protect the timers used for external signal acquisition and measurement, like “input capture” and “encoder reading”. The implementation is easy as it simply requires connecting the external signals also to the redundant timer, and performs a coherence check on the measured data at application level. To reduce the potential effect of the common cause failure, it is suggested, for redundancy, to use a channel belonging to a different timer module and mapped to not-adjacent pins on the device package.

### Loop-back scheme for PWM outputs –TIM\_SM\_3

This method uses a loop-back scheme to detect permanent and transient faults on the timer channels used for output waveform generations (output compare, PWM and one-pulse mode). It is implemented by connecting the output signal to a separate channel, either in the same or in another timer, to acquire the generated waveform characteristics.

The guidelines for the implementation of the method for the PWM signal are the following:

- Both frequency and duty cycle of PWM are measured and checked versus the expected value.
- To reduce the potential effect of common cause failure, it is suggested to use for the loop-back check a channel belonging to a different timer module and mapped to not-adjacent pins on the device package.

This measure can be replaced, under the end-user responsibility, by different loop-back schemes already in place in the final application and rated as equivalent. For example, if the PWM is used to drive an external power load, the measurement of the on-line current value can be used instead of the PWM frequency one.

## 3.6.13 Basic timer (TIM 4)

### Periodical read-back of configuration registers - BTIM\_SM\_0

This diagnostic measure that is typically referred to as “Read Back Periodic by Software of Configuration Registers” executes a periodical check of the configuration registers of TIMER respect to their expected values, previously stored in RAM and adequately updated after each configuration change. It mainly addresses transient faults affecting the



configuration registers, detecting bit flips. The registers test is executed at least once per DTI.

#### **Dual channel redundancy for counting timers - BTIM\_SM\_1**

This method provides a high level of coverage for both permanent and transient faults on the addressed timers. The method is conceived to protect the timers with counting features, for example the timers dedicated to maintain a system time base and/or to generate a timed interrupt for the execution of service routines (like for instance general timing counters update/increase).

The guidelines for the implementation of the method are the following:

- In case of timer used as a time base, use one of the timers as time-base source in the application software, and the other one just for check. In that case the coherence check for the dual channel redundancy will be done at application level.
- In case of interrupt generation usage, use the first timer as main interrupt source for the service routines, and use the second timer to activate a “checking routine” that cross-checks the coherence between the timers.

### **3.6.14 GPIO - Ports A/B/C/D/E/F/G/H**

#### **Periodical read-back of configuration registers - GPIO\_SM\_0**

This diagnostic measure that is typically referred to as “Read Back Periodic by Software of Configuration Registers” executes a periodical check of the configuration registers of GPIO respect to their expected values, previously stored in RAM and adequately updated after each configuration change. It mainly addresses transient faults affecting the configuration registers, detecting bit flips. The registers test is executed at least once per DTI.

#### **Dual channel redundancy for input GPIO lines - GPIO\_SM\_1**

To address both permanent and transient faults on GPIO lines used as input, it is required to implement a dual channel redundancy scheme by connecting the external safety-relevant signal to two independent GPIO lines. To reduce the potential impact of common cause failure, it is suggested to use GPIO lines belonging to different I/O ports (for example PORT A and B) and mapped to not-adjacent pins on the device package.

#### **Loop-back configuration for output GPIO lines - GPIO\_SM\_2**

To address both permanent and transient faults on GPIO lines used as output, it is required to implement a loop-back scheme, connecting the output to a different GPIO line programmed as input and used to check the expected value on output port. To reduce the potential impact of common cause failure, it is suggested to use GPIO lines belonging to different I/O ports (for example PORT A and B) and mapped to not-adjacent pins on the device package.

### **3.6.15 Address and Data bus**

#### **Periodical software test for interconnections - BUS\_SM\_0**

The intra-chip connection resources need to be periodically tested for permanent faults detection. Note that STM8AF MCUs have no hardware safety mechanism to protect these structures. The test executes a connectivity test of these shared resources, including the



testing of the arbitration mechanisms between peripherals. This method, based on the periodical execution of software-based tests is executed at least once per DTI.

Note that the implementation of this safety method is overlapped by already planned methods for the configuration register checks for the STM8AF peripherals (e.g. [CAN\\_SM\\_0](#)).

Implementation of all such methods is equivalent to the implementation of BUS\_SM\_0.

### Information redundancy in intra-chip data exchanges - BUS\_SM\_1

Both permanent and transient faults affecting the intra-chip connection features are addressed by information redundancy techniques implemented on the messages exchanged inside the MCU.

Note that the implementation of this safety method is overlapped by already planned methods related to information redundancy for the STM8AF peripherals (e.g. [CAN\\_SM\\_2](#)).

Implementation of all such methods is equivalent to the implementation of BUS\_SM\_1.

## 3.6.16 Supply voltage system

### Periodical read-back of configuration registers - VSUP\_SM\_0

This diagnostic measure that is typically referred to as “Read Back Periodic by Software of Configuration Registers” executes a periodical check of the configuration registers of the Power Control logic respect to their expected values, previously stored in RAM and adequately updated after each configuration change. It mainly addresses transient faults affecting the configuration registers, detecting bit flips. The registers test is executed at least once per DTI.

### Supply voltage monitoring - VSUP\_SM\_1

It is required to detect early the under voltage and overvoltage conditions that are potential sources of failure at MCU level. The power supply values close to the operating limits reported in device datasheet are considered at the same level as hardware faults and lead to similar recovery actions by the application software.

The usage of an external monitoring power supply device outside the MCU can ensure the protection against potential common cause failures.

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**Warning:** In order to reduce the risk of an overvoltage condition, it is highly recommended the end users to respect the absolute maximum ratings for voltage (see [Section 3.4: Electrical specifications and environment limits](#)).

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### Independent watchdog - VSUP\_SM\_2

The independent watchdog is fed directly by  $V_{DD}$ ; therefore, major failures in the 1.8 V supply for digital logic (core/peripherals) will not affect its behavior but may lead to a violation of the IWDG window for the key value writing by the application software, leading to a system reset.

### 3.6.17 Reset and Clock control subsystems

#### Periodical read-back of configuration registers - CLK\_SM\_0

This diagnostic measure that is typically referred to as “Read Back Periodic by Software of Configuration Registers” executes a periodical check of the configuration registers of the Reset and Clock Control logic respect to their expected values (previously stored in RAM and adequately updated after each configuration change). It mainly addresses transient faults affecting the configuration registers, detecting bit flips. The registers test is executed at least once per DTI.

#### Clock Security System (CSS) - CLK\_SM\_1

The Clock Security System (CSS) detects the loss of HSE and LSE clock activity and executes the corresponding recovery action, e.g. switch-off HSE and commute on the HSI. For this reason it is able to detect potential abnormal situations:

- Loss of external clock,
- Abnormal activation of HSE (or LSE) despite being disabled by design.

The CSS detection of abnormal condition is considered as equivalent to hardware faults and brings to similar recovery actions by the application software.

#### Independent watchdog - CLK\_SM\_2

The independent watchdog is fed by a dedicated oscillator; therefore, major failures on clock generation at system level will not affect its behavior but may lead to a violation of the IWDG window for the key value write by the application software, leading to a system reset. Note that the efficiency of this safety mechanism is strongly dependent on the correct window setting and handling for the IWDG. The refresh of the IWDG has to be implemented to bring alteration of the program flow able to bypass the time window limit.

### 3.6.18 Auto-wakeup timer (AWU)

The AWU is used to provide an internal wakeup time base that is used when the MCU goes into Active-halt power saving mode.

#### Periodical read-back of configuration registers - AWU\_SM\_0

This diagnostic measure that is typically referred to as “Read Back Periodic by Software of Configuration Registers” executes a periodical check of the configuration registers of the watchdogs respect to their expected values (previously stored in RAM and adequately updated after each configuration change). It mainly addresses transient faults affecting the configuration registers, detecting bit flips. The registers test is executed at least once per DTI.

#### Software test for auto-wakeup timer at startup - AWU\_SM\_1

This safety mechanism ensures the right functionality of the auto-wakeup timer. At startup, the software test programs the auto-wakeup timer with the required time interval, stores a specific flag in the RAM and waits for the reset signal. After the wake-up, the software understands that the AWU has correctly triggered, and does not execute the procedure again. This method has to be applied only in case the implemented safety goal will plan the use of the auto-wakeup feature.

### 3.6.19 Watchdogs (IWDG, WWDG)

#### Periodical read-back of configuration registers - WDG\_SM\_0

This diagnostic measure that is typically referred to as “Read Back Periodic by Software of Configuration Registers” executes a periodical check of the configuration registers of the watchdogs respect to their expected values (previously stored in RAM and adequately updated after each configuration change). It mainly addresses transient faults affecting the configuration registers, detecting bit flips. The registers test is executed at least once per DTI.

#### Software test for watchdog at startup - WDG\_SM\_1

This safety mechanism ensures the right functionality of the internal watchdogs in use. At startup, the software test programs the watchdog with the required expiration timeout, stores a specific flag in the RAM and waits for the reset signal. After the watchdog reset, the software understands that the watchdog has correctly triggered, and does not execute the procedure again.

### 3.6.20 Debug/SWIM (single wire interface module)

#### Independent watchdog - DBG\_SM\_0

The debug unintentional activation due to hardware random fault will result in the massive disturbance of the independent watchdog or alternately, the other system watchdog WWDG or an external one.

### 3.6.21 Interrupt controller (NVIC and EXTI)

#### Periodical read-back of configuration registers - INTC\_SM\_0

This diagnostic measure that is typically referred to as “Read Back Periodic by Software of Configuration Registers” is implemented by executing a periodical check of the configuration registers of each used system peripheral respect to its expected value, previously stored in RAM and adequately updated after each configuration change. It mainly addresses the transient faults that affect the configuration registers, by detecting bit flips. The register test is executed at least once per DTI.

#### Expected and unexpected interrupt check - INTC\_SM\_1

According to ISO 26262-5 Table D.1 recommendations, a safety mechanism/measure for incorrect interrupt executions and for omission of or continuous interrupts must be implemented. The method of expected and unexpected interrupt check is implemented at application software level. It contributes to detect both permanent and transient fault for all the above-reported failure modes affecting interrupt handling.

The guidelines for the implementation of the method are the following:

- The list of the implemented interrupt for the MCU is well documented, reporting also the expected frequency of each request when possible (for example the interrupts related to ADC conversion completion, therefore coming on a deterministic way).
- Individual counters are maintained for each served interrupt request, in order to detect in a given time frame the cases of a) no interrupt at all b) too many interrupt requests (“babbling idiot” interrupt source). The control of the time frame duration shall be

regulated according to the individual interrupt expected frequency.

- Interrupt vectors related to unused interrupt source point to a default handler that will report, in case of triggering, a faulty condition (unexpected interrupt).
- In case an interrupt service routine is shared between different sources, a plausibility check on the caller identity is implemented.
- Interrupt requests related to not-safety-relevant peripherals are handled with the same method here described, despite their originator safety classification; in order to decrease the complexity of this method implementation, the use of polling instead of interrupt for not-safety-relevant peripherals is suggested.

### 3.6.22 Latent fault detection

ISO 26262 considers also a metric for “latent” faults. The latent fault is a multiple-point fault which presence is not detected by a safety mechanism nor perceived by the driver within the multiple-point fault detection interval. In practical words, the latent fault is a combination of a fault in a safety mechanism - that by itself will NOT cause the violation of the safety goal (function) - and a fault in the mission logic supervised by that safety mechanism.

The following reported methods mainly address latent fault for the planned safety mechanism at MCU level.

#### Independent Watchdog - LAT\_SM\_0

Each safety mechanism implemented as periodical software testing runs on the CPU. Possible faults in the safety mechanism are therefore faults in the “support” for the execution that is the CPU. The independent watchdog is considered here as safety mechanism addressing the program counter failures due to the CPU hardware random faults.

#### Periodical core self-test software - LAT\_SM\_1

As the major part of the safety mechanism described in this safety manual is implemented by software, the periodical core self-test software execution able to detect faults in the STM8 CPU acts as safety mechanism for latent faults. For implementation details refer to the description of [CPU\\_SM\\_0](#) safety mechanism.

### 3.6.23 Disable and periodic cross-check of unintentional activation of unused peripherals

This section reports the safety mechanism that addresses peripherals not used by the safety application, or not used at all.

#### Unused peripherals disable - FFI\_SM\_0

This method contributes to the reduction of the probability of cross-interferences caused by peripherals not used by the software application. It is implemented by end users, taking care of disabling by software (for instance during the system boot) each peripheral that is not used.

#### Periodical read-back of interference avoidance registers - FFI\_SM\_1

This method contributes to the reduction of the probability of cross-interferences between peripherals that can potentially conflict on the same output pins, including for instance unused peripherals (refer to FFI\_SM\_0). This diagnostic measure executes a periodical

check of the below described registers respect to their expected values (previously stored in RAM and adequately updated after each configuration change). The register test is executed at least once per DTI.

The configuration registers to be tested with this method are those related to clock disabling features for peripherals and those related to the enabling of alternate functions on I/O pins.

## 3.7 Assumption of Use (AoU)

This section describes the Assumptions of Use (AoU) of the STM8AF that the MCU/system integrator will consider (together with the requirements listed in [Table 2: List of STM8AF assumed requirements](#)) with respect to its intended use.

The AoUs are different from the HW safety requirements of STM8AF. The AoUs are requirements for the MCU/system integrator.

### 3.7.1 List of AoUs

The following tables summarize the Assumptions of Use (AoU) to be fulfilled by users of the STM8AF MCUs.

The results shown in [Section 4: Safety analysis results](#) are valid under the condition that the AoU, described herein, and the assumed requirements listed in [Table 2](#), are fulfilled by the STM8AF MCU/system integrator.

The following table lists the assumptions of use and for each of them shows the degree of recommendation using the typical ISO 26262 coding in order to keep the text consistent with the standard and to facilitate their interpretation by the user. For each AoU, the degree of recommendation to use the corresponding method depends on the ASIL and is categorized as follows:

- “++” indicates that the assumption is highly recommended for the identified ASIL
- “+” indicates that the assumption is recommended for the identified ASIL
- “o” indicates that the assumption has no recommendation for or against its usage for the identified ASIL.

[Table 4](#) provides a summary of the safety concept recommendations reported in [Section 3.6](#).

The assumptions of use are reported in the form of safety mechanism (SM) requirements.

The “X” marker in the *Perm* and *Trans* columns of [Table 4](#) indicates that the related safety mechanism is effective for such fault model.

Table 4. List of safety mechanisms

STM8AF function	Diagnostic	Description	ASIL B	Perm	Trans
STM8 core	CPU_SM_0	Periodical core self-test software	++	X	-
	CPU_SM_1	Control flow monitoring in application software	++	X	X
	CPU_SM_2	Double computation in application	++	-	X
	CPU_SM_3	Stack hardening for application software	+	X	X
	CPU_SM_4	Independent watchdog	o	X	X
Program Flash memory	FLASH_SM_0	Periodical software test for Flash memory	++	X	-
	FLASH_SM_1	Control flow monitoring in application software	+	X	X
	FLASH_SM_3	Option byte write protection	M	-	-
Data EEPROM	EEP_SM_0	Information redundancy	++	X	-
	EEP_SM_1	Software read-back after write operation	+	X	X
RAM	RAM_SM_0	Periodical software test for RAM	++	X	-
	RAM_SM_1	Stack hardening for application software	+	X	X
	RAM_SM_2	Information redundancy for system variables in application software	++	X	X
Boot ROM	ROM_SM_0	Control flow monitoring in application software	++	X	-
beCAN	CAN_SM_0	Periodical read-back of configuration registers	++	X	X
	CAN_SM_1	Protocol error signals	+	X	X
	CAN_SM_2	Information redundancy techniques on messages, including End to End safing	++	X	X
LINUART	LINUART_SM_0	Periodical read-back of configuration registers	++	X	-
	LINUART_SM_1	Protocol error signals	+	X	X
	LINUART_SM_2	Information redundancy techniques on messages	++	X	X
UART	UART_SM_0	Periodical read-back of configuration registers	++	X	X
	UART_SM_1	Protocol error signals	+	X	X
	UART_SM_2	Information redundancy techniques on messages	++	X	X
I2C	IIC_SM_0	Periodical read-back of configuration registers	++	X	X
	IIC_SM_1	Protocol error signals	+	X	X
	IIC_SM_2	Information redundancy techniques on messages	++	X	X

Table 4. List of safety mechanisms (continued)

STM8AF function	Diagnostic	Description	ASIL B	Perm	Trans
SPI	SPI_SM_0	Periodical read-back of configuration registers	++	X	X
	SPI_SM_1	Protocol error signals	+	X	X
	SPI_SM_2	Information redundancy techniques on messages	++	X	X
ADC	ADC_SM_0	Periodical read-back of configuration registers	++	X	X
	ADC_SM_1	Multiple acquisition by application software	++	-	X
	ADC_SM_2	Range check by application software	++	X	X
	ADC_SM_3	Periodical software test for ADC	+	X	-
TIM1 and TIM2/3	TIM_SM_0	Periodical read-back of configuration registers	++	X	X
	TIM_SM_1	Dual channel redundancy for counting timers	++	X	X
	TIM_SM_2	Dual channel redundancy for input capture timers	++	X	X
	TIM_SM_3	Loop-back scheme for PWM outputs	++	X	X
TIM4	BTIM_SM_0	Periodical read-back of configuration registers	++	X	X
	BTIM_SM_1	Dual channel redundancy for counting timers	++	X	X
GPIO	GPIO_SM_0	Periodical read-back of configuration registers	++	X	X
	GPIO_SM_1	Dual channel redundancy for input GPIO lines	++	X	X
	GPIO_SM_2	Loop-back scheme for output GPIO lines	++	X	X
	GPIO_SM_3	GPIO port configuration lock register	+	-	-
Address and Data bus	BUS_SM_0	Periodical software test for interconnections	++	X	-
	BUS_SM_1	Information redundancy in intra-chip data exchanges	++	X	X
Supply voltage system	VSUP_SM_0	Periodical read-back of configuration registers	++	X	X
	VSUP_SM_1	Supply voltage monitoring	++	X	-
	VSUP_SM_2	Independent watchdog	++	X	-
Clock and Reset	CLK_SM_0	Periodical read-back of configuration registers	++	X	X
	CLK_SM_1	CSS (Clock Security System)	++	X	-
	CLK_SM_2	Independent watchdog	++	X	-
	CLK_SM_3	Internal clock cross-measure	+	X	-

**Table 4. List of safety mechanisms (continued)**

STM8AF function	Diagnostic	Description	ASIL B	Perm	Trans
WAURTC	WAU_SM_0	Periodical read-back of configuration registers	++	X	X
	WAU_SM_1	Software test for auto-wakeup timer at startup	+	X	X
WWDG and IWDG	WDG_SM_0	Periodical read-back of configuration registers	++	X	X
	WDG_SM_1	Software test for watchdog at startup	o	X	-
Debug	DBG_SM_0	Independent watchdog	++	X	X
Interrupt controller	INTC_SM_0	Periodical read-back of configuration registers	++	X	X
	INTC_SM_1	Expected and unexpected interrupt check by application software	++	X	X
Software-based safety	LAT_SM_0	Independent watchdog	+	X	-
	LAT_SM_1	Periodical core self-test software	+	X	-
Part separation (no interference)	FFI_SM_0	Unused peripherals disable	++	-	-
	FFI_SM_1	Periodical read-back of interference avoidance registers	++	-	-

The above-described safety mechanism/measures are implemented with different levels of abstraction, depending on their nature: the more a safety mechanism is implemented as application-independent, the wider is its possible use on a wide range of end-user applications.



## 4 Safety analysis results

This section reports the results of the safety analysis of the STM8AF MCU, according to ISO 26262 (in particular ISO 26262-10 Annex A).

ISO 26262-10 Annex A is a guideline about how to perform a safety analysis of a microcontroller according to ISO 26262.

Shortly, the ISO 26262 has three main objectives:

- To improve functional safety by reducing the **HW random failures**, i.e. failures that can occur unpredictably during the lifetime of a hardware element and that follow a probability distribution. They are quantified using safety “metrics”, as described in [Section 3.3.1: The target safety metrics \(ASIL, SPFM, LFM and PMHF\)](#).
- To improve functional safety by reducing or avoiding **dependent failures**, i.e. failures whose probability of simultaneous or successive occurrence cannot be expressed simply as the product of the unconditional probability of each failure. They include common cause failures and cascading failures. They are analyzed in a qualitative way by means of checklists, as described in [Section 4.2: Dependent failures analysis](#).
- To reduce or avoid the **systematic failures**, i.e. failures, related in a deterministic way to a certain cause, that can only be eliminated by a change of the design or of the manufacturing process, operational procedures, documentation or other relevant factors.

As mentioned before, the target for the safety functions is ASILB; therefore every consideration about absolute and relative safety metrics will take ASILB targets.

It is worth to recap here that ASILB report as target limits 90% for SPF (overall system) and 100 FIT for PMHF (100 FIT is indeed the overall budget available for the system, therefore for STM8AF the allocated budget will be lower).

### 4.1 Hardware random failure analysis

The analysis for random hardware failures of STM8AF devices reported in this safety manual is executed according to ISO 26262 and to the following steps.

The STM8AF has been divided into parts and sub-parts according to the procedure defined in ISO 26262-10. Then, for each part and sub-part, the failure modes have been identified starting from the ones specified by ISO 26262-5, Annex D and then significantly extended based on detailed analyses.

Each failure mode has been analyzed in terms of its “end effect” at the STM8AF I/O level. Detailed results of the qualitative analysis are reported in [\[2\]](#).

About safety metrics, both relative (SPFM, LFM) and absolute (PMHF) have been computed. The results are not reported in this section but in [\[2\]](#).

In summary, with the adoptions of the safety mechanism and conditions of use reported in [Section 3.7: Assumption of Use \(AoU\)](#), it is possible for the STM8AF family devices to achieve the ASILB target.

### 4.1.1 Safety analysis result customization

The safety analysis executed for STM8AF devices and contained in this safety manual is considered to be safety relevant, that is able to interfere with the safety function, to all microcontroller parts, with no exclusion. This is in line with the conservative approach to be followed during the analysis of a general-purpose microcontroller, in order to be agnostic versus the final application. This means that no STM8AF module has been declared as “non safety-related”, and therefore all STM8AF modules are included in SPF computations.

In end-user applications, not all the STM8AF parts/modules are used for the implementation of the safety function. Requiring the implementation of the respective safety mechanism for those parts could result in overkill; as a consequence, a dedicated analysis has been done. According to this analysis, the end user can define the selected STM8AF parts as “non safety-related” under the following conditions:

- collect rationales and evidences that the parts play no role in safety function implementation
- collect rationales and evidences that the parts do not interfere with the safety function during normal operation
- fulfill the below-reported general condition for the mitigation of the intra-MCU interferences ([Table 5](#))

The end user is allowed for “non safety-related” parts to do the following:

- discard the part contribution from metrics computations in FMEDA
- not implement the related safety mechanisms listed in [Table 3](#).

See [\[1\]](#) for more information.

### 4.1.2 General requirements for Freedom From Interferences (FFI)

A dedicated analysis has highlighted a list of general requirements to be followed by end users in order to be authorized to declare selected STM8AF parts as “not safety relevant”. The analysis considers two situations: the part that is not used at all (disabled) or the part is used for a function that is not safety-related (for example a GPIO port driving a “power-on” signaling led on the electronic board), and considers the possible interferences due to hardware random faults affecting not-safety-relevant parts.

The requirement for the end user is to implement the safety mechanism detailed in [Diagnostic](#) despite any evaluation about their contribution for the safety metrics computations. Those safety mechanisms are reported in [Table 5](#).

**Table 5. List of general requirements for FFI**

Diagnostic	Description
INTC_SM_0	Periodical read-back of configuration registers
INTC_SM_1	Expected and unexpected interrupt check by application software
FFI_SM_0	Unused peripheral disable
FFI_SM_1	Periodical read-back of interference avoidance registers
BUS_SM_0	Periodical software test for interconnections
GPIO_SM_1	Dual channel redundancy for input GPIO lines
GPIO_SM_2	Loop-back configuration for output GPIO lines

[AR08](#) is a consequence of the performed FFI analysis.

## 4.2 Dependent failures analysis

The analysis of dependent failures is important for microcontrollers. The main sub-classes of dependent failures are the Common Cause Failures (CCF).

According to ISO 26262 they need to be addressed on a qualitative basis (ISO 26262-9:2011, 7.4.1 Note3) but an evaluation can be supported by appropriate checklists.

Measures for the resolution of CCF need to include the measures for preventing their root causes, or for controlling their effects, or for reducing the coupling factors. The ISO 26262-10:2011, Annex A includes a paragraph dedicated to initiators and measures for dependent failures. The ISO 26262-9:2011, 7.4.4 Note1 says that IEC 61508 provides information that can be used as a basis to establish such checklists. Anyway, as there are no on-chip redundancies on STM8AF devices, the CCF quantification through BetaIC computation method is not required.

The STM8AF device architecture and structure are potential sources of dependent failures. These are analyzed in the following sections. The referred safety mechanisms are described in detail in [Section 3.6: Safety mechanisms/measures](#).

### 4.2.1 Power supply

Power supply is a potential source of dependent failures, because any alteration of the power the supply can affect many parts, leading to not-independent failures. The following safety mechanisms address and mitigate those dependent failures:

- VSUP\_SM\_1: detection of abnormal value of supply voltage;
- VSUP\_SM\_2: the independent watchdog has a different supply source from the digital core of the MCU, and this diversity helps to mitigate dependent failures related to the main supply alterations.

The adoption of such safety mechanisms is therefore strongly recommended despite their minor contribution to the safety metrics to reach the required safety integrity level. Refer to [Section 3.6.16: Supply voltage system](#) for the detailed safety mechanism descriptions.

### 4.2.2 Clock

System clocks are a potential source of dependent failures, because alterations in the clock characteristics (frequency, jitter) can affect many parts, leading to not-independent failures. The following safety mechanisms address and mitigate those dependent failures:

- CLK\_SM\_1: the clock security system is able to detect hard alterations (stop) of system clock and activate the adequate recovery actions.
- CLK\_SM\_2: the independent watchdog has a dedicated clock source. The frequency alteration of the system clock leads to the watchdog window violations by the triggering routine on the application software, leading to the MCU reset by watchdog.

The adoption of such safety mechanism is therefore strongly recommended despite their minor contribution to the safety metrics to reach the required safety integrity level. In particular, the use of system watchdog WWDG increases the overall capability to keep the program flow under control.

Refer to [Section 3.6.17](#) for detailed safety mechanisms description.

## 5 List of evidences

The Safety Case stores all the information related to the safety analysis performed to derive the results and conclusions reported in this safety manual.

These contents are not public, but can be made available for possible competent bodies audit and inspections.

## Appendix A Change impact analysis for other safety standards

The safety analysis reported in this user manual is carried out according to ISO 26262 safety norm. In this appendix a change impact analysis with respect to different safety standard is performed. The following topics are considered for each addressed safety norm:

- Differences in the suggested hardware architecture (architectural categories), and how to map what is foreseen in the new safety norm on the standard safety architectures of ISO 26262.
- Differences in the safety integrity level definitions and metrics computation methods, and how to recompute and judge the safety performances of STM8AF devices according to the new standard.
- Work products required by the new safety norms, and how to remap or rework if needed existing ones resulting as output of the ISO 26262 compliance activity.

The safety standard examined within this change impact analysis is the following:

- IEC 61508:1-7 – ed. 2 ©IEC: 2010: Functional safety of electrical/electronic/programmable electronic safety-related systems.

### A.1 IEC 61508

The IEC 61508 is the international norm for functional safety of electrical/electronic/programmable electronic (E/E/PE) safety-related systems.

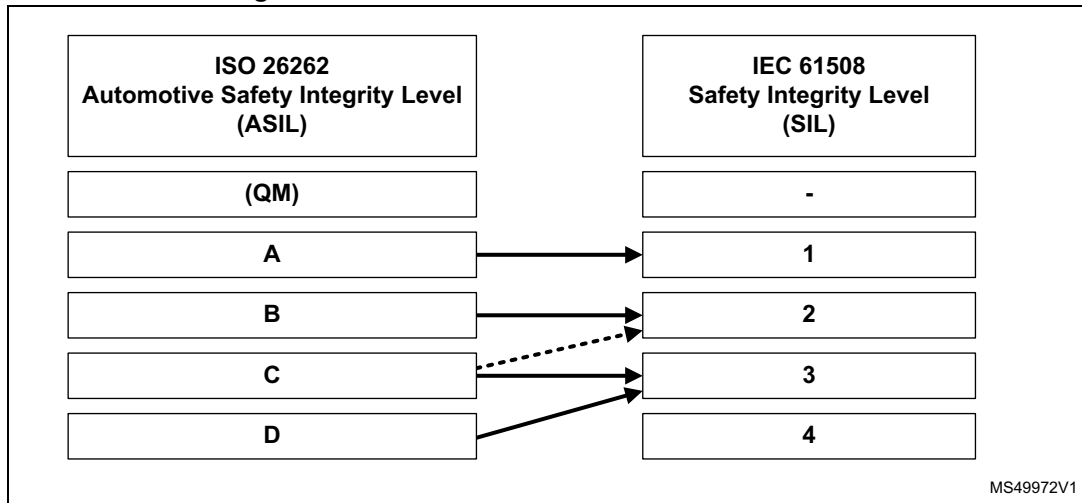
The ISO 26262 standard is derived from the IEC 61508 standard.

As ISO 26262, the IEC 61508 standard defines four safety integrity levels (SILs), based on the assessment of the hazard and risk analysis, with SIL1 being the lowest and SIL4 being the highest.

Despite Automotive Level of Safety Integrity (ASIL) defined in ISO 26262 (with a scale from A, the lowest level, to D, the highest level), comes from its parent standard SIL definition, there is no direct correlation between IEC 61508 and ISO 26262 ASIL levels as the ASIL in ISO 26262 is not stated in probabilistic terms while the SIL in IEC 61508 it is.

A correlation matrix between SIL and ASIL values has been empirically identified by TÜV SÜD and is illustrated in [Figure 4](#).

Figure 4. Correlation matrix between SIL and ASIL



In the IEC 61508 scope, end-users can rely on SIL decomposition to define system architectures where the highest SIL requirements are fulfilled by using lower SILs redundant sub systems but respecting the requirements in part 2 §7.4.4.2.4. Following the rules, an SIL3 safety goal can be decomposed leading to an item made of two SIL2 independent elements. Thus, end-users can positively match SEooC assumptions in the form of STM8AF AoU (refer to [Section 3.7: Assumption of Use \(AoU\)](#)). Then the safety requirements of the system under development can integrate the STM8AF MCU together with the related safety mechanisms defined in this manual, in items performing up to SIL3 safety functions.

### A.1.1 Architectural categories

IEC 61508-6, Annex B requires representing a safety system by means of subsystem block diagram and representing each subsystem as one or more 1oo1, 1oo2, 2oo2, 1oo2D, 1oo3 or 2oo3 voted groups.

In principle, the safety architectures targeted in this document can be mapped to “1oo1” or “1oo1d” if HFT = 0 is selected, or “1oo2” or “1oo2d if HFT = 1 if selected (see [Table 6](#)).

Table 6. Some reference architectures for IEC 61508

Architecture	Hardware fault tolerance (HFT)	Description
1oo1	0	Architecture of a single set of components/ component having no hardware fault tolerance. Failure of a unit can lead to a loss of the safety function.
1oo1d	0	Architecture of a single set of components/ component with a diagnostic section, having no hardware fault tolerance. Failure of a unit can lead to a loss of the safety function.
1oo2	1	Architecture of two set of components/ component connected in parallel, having a hardware fault tolerance of 1. Failure of a unit does not lead to a loss of the safety function.

Table 6. Some reference architectures for IEC 61508 (continued)

Architecture	Hardware fault tolerance (HFT)	Description
1oo2d	1	Architecture of two set of components / component connected in parallel with a diagnostic section, having a hardware fault tolerance of 1. Failure of a unit does not lead to a loss of the safety function.
2oo2	0	Architecture of two set of components/ component connected in parallel, having no hardware fault tolerance. In 2oo2 the diagnostic section is optional.

Even if the ISO 26262 does not define any reference architecture, the description of the SEooC made in this document ([Section 3.2: STM8AF as a SEooC](#)) and its representation by means of the block diagram represented in [Figure 1](#), allow mapping the SEooC to the 1oo1 architecture, including the STM8AF microcontroller as compliant item.

The reference block diagram of such architecture will be the same represented in [Figure 1](#), simply replacing the word “SEooC” with “Compliant item”.

If a mapping to a different architecture (1oo2, 1oo2d or 2oo2 architecture) is required, the user has to make reference to the part 6 of the IEC 61508 (IEC 61508-8).

### A.1.2 Safety metrics re-computation

Hardware metrics in IEC 61508 standard have been defined with a slightly different perspective with respect to the ISO 26262.

IEC 61508 is mainly focused on the capability of identification of the safe failure fraction (SFF), defined as the percentages of failures that are safe or detected and so do not lead to the violation of a safety goal. The mathematic definition for SFF is identical to the one for SPF in ISO 26262.

Latent faults are Not Applicable, as IEC 61508 does not define this metric.

Considering the metrics computation, the main differences between IEC 61508 and ISO 26262 are related to how the safe faults are computed and how the failure rate of diagnostic is computed with the mission.

The differences in failure rates related to hardware diagnostics are assumed to be negligible; hardware-native safety failures in STM8AF are very few, and with very little weight in terms of gate count. Therefore, the safety analysis already performed for SPF target can be reused for the SFF targets in IEC.

For such kind of Commercial Off-the-Shelf (COTS) microcontroller, the natural target in IEC scenario is 1oo1 SIL 2 (90% is the SFF target for permanent and transient). As these are the same targets for ASILB case, one can assume that the same set of conditions of use/safety mechanisms apply.

Metrics computations are detailed in [\[2\]](#).

### A.1.3 Work products

*Table 7*, mapping this document content with respect to the requirements listed in the IEC 61508-2 Annex D, acts as a checklist in guidance in providing the evidences of the compliance of the IEC 61508 requirements.

**Table 7. Mapping between this document content and IEC 61508-2 Annex D requirements**

IEC 61508 requirement (part 2 annex D)	Reference
D2.1 a) a functional specification of the functions capable of being performed	<a href="#">Section 3: STM8AF safety architecture</a>
D2.1 b) identification of the hardware and/or software configuration of the compliant item	<a href="#">Section 3.2: STM8AF as a SEooC</a>
D2.1 c) constraints on the use of the compliant item and/or assumptions on which analysis of the behavior or failure rates of the item are based	<a href="#">Section 3.2: STM8AF as a SEooC</a>
D2.2 a) the failure modes of the compliant item due to random hardware failures, that result in a failure of the function and that are not detected by diagnostics internal to the compliant item;	<a href="#">Section 3.7: Assumption of Use (AoU)</a>
D2.2 b) for every failure mode in a), an estimated failure rate;	
D2.2 c) the failure modes of the compliant item due to random hardware failures, that result in a failure of the function and that are detected by diagnostics internal to the compliant item;	
D2.2 d) the failure modes of the diagnostics, internal to the compliant item due to random hardware failures, that result in a failure of the diagnostics to detect failures of the function;	
D2.2 e) for every failure mode in c) and d), the estimated failure rate;	
D2.2 f) for every failure mode in c) that is detected by diagnostics internal to the compliant item, the diagnostic test interval;	<a href="#">Section 3.3: Assumed safety requirements</a>
D2.2 g) for every failure mode in c) the outputs of the compliant item initiated by the internal diagnostics;	<a href="#">Section 3.2: STM8AF as a SEooC</a>
D2.2 h) any periodic proof test and/or maintenance requirements;	<a href="#">Section 3.7: Assumption of Use (AoU)</a>
D2.2 i) for those failure modes, in respect of a specified function, that are capable of being detected by external diagnostics, sufficient information shall be provided to facilitate the development of an external diagnostics capability.	
D2.2 j) the hardware fault tolerance;	<a href="#">Section 3: STM8AF safety architecture</a>
D2.2 k) the classification as type A or type B of that part of the compliant item that provides the function (see 7.4.4.1.2 and 7.4.4.1.3);	

*Table 8* lists the work products required by the IEC 61508 standard and their mapping with the work products from ISO 26262 compliance activity:



Table 8. IEC 61508 work product grid

IEC 61508		ISO 26262		
Information to be provided	IEC 61508-2	Reference	Part 4 Clause	Document
Design requirements specification	7.2.2	Technical safety requirements specification	6.5.1	Safety manual
Design requirements specification relating to safety functions	7.2.3.2			
Design requirements specification relating to safety integrity	7.2.3.3			
Safety validation planning	7.3.2	Validation plan	6.5.3	End user responsibility
E/E/PE system design and development	7.4.2 to 7.4.11	System design	7.5.1 to 7.5.4	
Integration	7.5.2	Item integration and testing plan Integration testing specification(s) Integration testing report(s)	8.5.1 to 8.5.3	
E/E/PE system installation, commissioning, operation and maintenance procedures	7.6.2	-	-	
E/E/PE system safety validation	7.7.2	Validation report	9.5.2	
E/E/PE system modification	7.8.2	-	-	
E/E/PE system verification	7.9.2	System verification report	6.5.2	
Functional safety assessment	8	Functional safety assessment report	10.5.1	

## Revision history

**Table 9. Document revision history**

Date	Revision	Changes
07-Jul-2015	1	Initial version.
18-May-2018	2	<p>Updated <i>Introduction</i>, <i>Section 1.3: Reference normative</i>, <i>Section 1.4: Annexes</i>, <i>Section 3.4: Electrical specifications and environment limits</i>, <i>Section 3.6: Safety mechanisms/measures</i>, <i>Section 4: Safety analysis results</i>, <i>Section 4.1: Hardware random failure analysis</i>, <i>Section 4.1.1: Safety analysis result customization</i>, <i>Section 4.1.2: General requirements for Freedom From Interferences (FFI)</i>, <i>Section 4.2: Dependent failures analysis</i>, <i>Section 5: List of evidences</i>, <i>Appendix A: Change impact analysis for other safety standards</i> and its subsections.</p> <p>Updated <i>Table 2: List of STM8AF assumed requirements</i>, <i>Table 4: List of safety mechanisms</i>, <i>Table 6: Some reference architectures for IEC 61508</i> and <i>Table 8: IEC 61508 work product grid</i>.</p> <p>Updated <i>Figure 1: Definition of the STM8AF as a SEooC</i>, <i>Figure 2: Relationship between assumptions and SEooC development</i>, <i>Figure 3: STM8AF FTTI allocation and cycle time</i> and <i>Figure 4: Correlation matrix between SIL and ASIL</i>.</p> <p>Removed former <i>Section 2.2: YOGITECH fRMethodology process</i>, <i>Appendix A: Overview of fRMethodology</i>, <i>B.1: IEC 60730-1:2010</i>, <i>B.2: Architectural categories</i>, <i>B.3: Safety metrics re-computation</i> and <i>B.4: Work products</i>.</p> <p>Minor text edits across the whole document.</p>

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